

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No. 09/546,174 Application of: Chih-Chien Liu, Ta-Shan Tseng, W. B. Shieh, J. Y. Wu, Water Lur and Shih-Wei Sun Filed: April 11, 2000 Attorney Docket No. UMC-96-279 CON For: HIGH DENSITY PLASMA CHEMICAL VAPOR DEPOSITION PROCESS	Confirmation No.: 4793 Art Unit: 1711 Examiner: Sergent, Rabon A. Customer No.: 25235
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RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT
DATED MAY 2, 2007

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims
beginning on page 2 of this paper.

Remarks begin on page 11 of this paper.